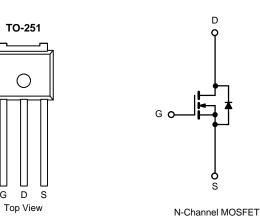


2SK2415-VB Datasheet

N-Channel 60 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | |
|---------------------|----------------------------------|--------------------|-----------------------|--|--|
| V _{DS} (V) | R _{DS(on)} (Ω) | I _D (A) | Q _g (Typ.) | | |
| 60 | 0.032 at V_{GS} = 10 V | 35 ^d | 21.7 | | |
| 00 | 0.037 at V _{GS} = 4.5 V | 30 ^d | 21.7 | | |



FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET .
- 100 % R_g and UIS Tested •
- Compliant to RoHS Directive 2002/95/EC ٠

APPLICATIONS

- Power Supply
- Secondary Synchronous Rectification
- DC/DC Converter

| ABSOLUTE MAXIMUM RATINGS | $T_{\rm C} = 25$ °C, unless oth | erwise noted | | | |
|--|-------------------------------------|-----------------------------------|-------------------|------|--|
| Parameter | | Symbol | Limit | Unit | |
| Drain-Source Voltage | | V _{DS} | 60 | V | |
| Gate-Source Voltage | | V _{GS} | ± 20 | | |
| Continuous Drain Current ($T_1 = 150 \ ^{\circ}C$) | T _C = 25 °C | L | 35 ^d | | |
| Continuous Drain Current (1) = 150°C) | T _C = 70 °C | I _D | 30 ^d | A | |
| Pulsed Drain Current | | I _{DM} | 100 | | |
| Avalanche Current | | I _{AS} | 40 | | |
| Single Avalanche Energy ^a | L = 0.1 mH | E _{AS} | 80 | mJ | |
| | T _C = 25 °C | P | 59.5 ^b | 14/ | |
| Maximum Power Dissipation ^a | T _A = 25 °C ^c | P _D | 2.7 | W | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 150 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | |
|--|-------------------|-------|------|--|--|
| Parameter | Symbol | Limit | Unit | | |
| Junction-to-Ambient (PCB Mount) ^c | R _{thJA} | 46 | °C/W | | |
| Junction-to-Case (Drain) | R _{thJC} | 2.1 | | | |

Notes:

a. Duty cycle \leq 1 %.

G

b. See SOA curve for voltage derating.c. When mounted on 1" square PCB (FR-4 material).

d. Package limited.

HALOGEN FREE

| SPECIFICATIONS $T_J = 25^{\circ}$ | C, unless o | therwise noted | | | | | |
|---|----------------------|---|------|-------|-------|------|--|
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
| Static | | - | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{DS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$ | 60 | | | .5 V | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$ | 2.0 | | 3.5 | | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 V, V_{GS} = \pm 20 V$ | | | ± 250 | nA | |
| | | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$ | | | 1 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$ | | | 50 | μA | |
| | | $V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 150 ^{\circ}\text{C}$ | | | 250 | 1 | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$ | 50 | | | А | |
| Drain-Source On-State Resistance ^a | Р | V _{GS} = 10 V, I _D = 12 A | | 0.032 | | 0 | |
| Drain-Source On-State Resistance | R _{DS(on)} | $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$ | | 0.037 | | Ω | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 15 V, I _D = 10 A | | 110 | | S | |
| Dynamic ^b | | - | | | | | |
| Input Capacitance | C _{iss} | | | 1100 | | pF | |
| Output Capacitance | C _{oss} | V _{GS} = 0 V, V _{DS} = 30 V, f = 1 MHz | | 281 | | | |
| Reverse Transfer Capacitance | C _{rss} | | | 130 | | | |
| Total Gate Charge ^c | Qg | $V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$ | | 46 | | nC | |
| Iolai Gale Charge | | | | 28 | | | |
| Gate-Source Charge ^c | Q _{gs} | $V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$ | | 7 | | | |
| Gate-Drain Charge ^c | Q _{gd} | | | 6.7 | | | |
| Gate Resistance | Rg | f = 1 MHz | 0.4 | 2 | 4 | Ω | |
| Turn-On Delay Time ^c | t _{d(on)} | | | 8 | 16 | | |
| Rise Time ^c | t _r | V_{DD} = 30 V, R _L = 1.5 Ω | | 9 | 18 | - ns | |
| Turn-Off Delay Time ^c | t _{d(off)} | $I_D \cong 10$ Å, $V_{GEN} = 10$ V, $R_g = 1$ Ω | | 35 | 53 | | |
| Fall Time ^c | t _f | | | 9 | 18 | | |
| Drain-Source Body Diode Ratings a | nd Characteri | stics T _C = 25 °C ^b | | · | | | |
| Continuous Current | ا _s | | | | 50 | ٨ | |
| Pulsed Current | I _{SM} | | | 1 | 100 | A | |
| Forward Voltage ^a | V _{SD} | I _F = 10 A, V _{GS} = 0 V | | 0.75 | 1.5 | V | |
| Reverse Recovery Time | t _{rr} | | | 34 | 51 | ns | |
| Peak Reverse Recovery Current | I _{RM(REC)} | I _F = 10 A, dl/dt = 100 A/μs | | 2 | 3 | А | |
| Reverse Recovery Charge | Q _{rr} | | | 34 | 51 | nC | |

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

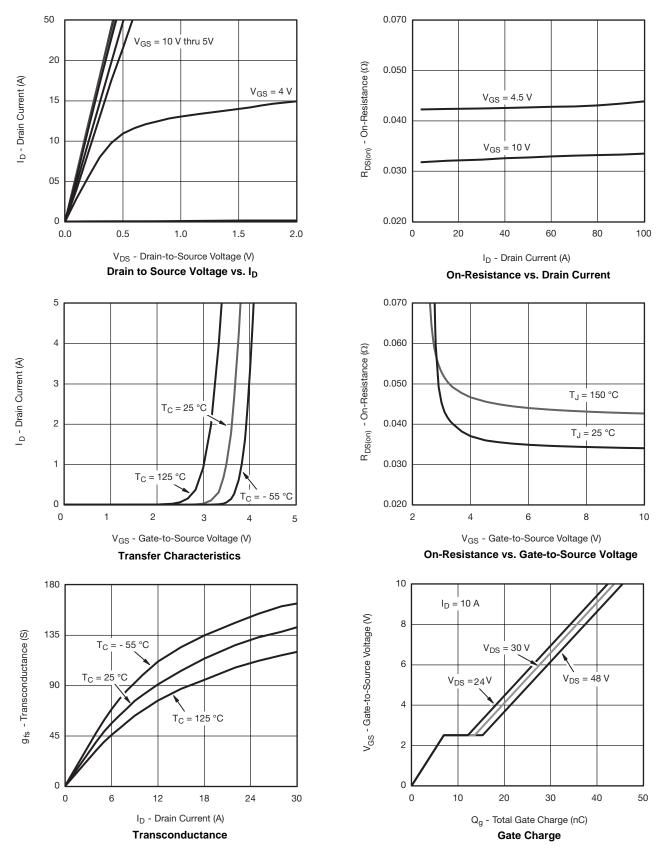
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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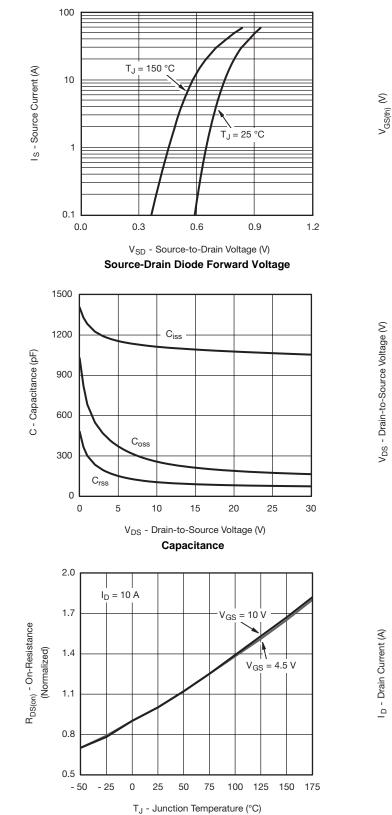
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



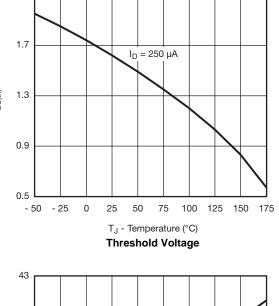
2SK2415-VB



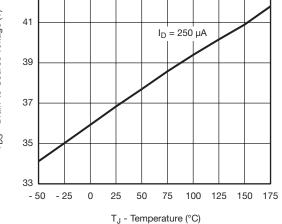
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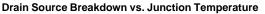


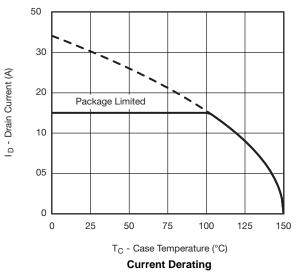
On-Resistance vs. Junction Temperature



2.1



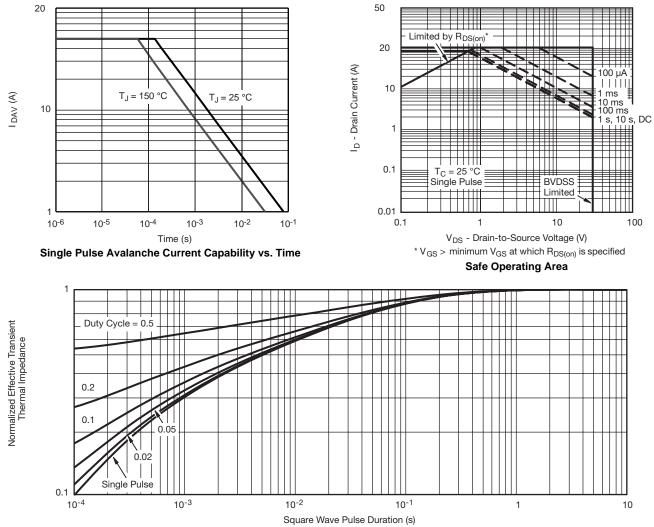








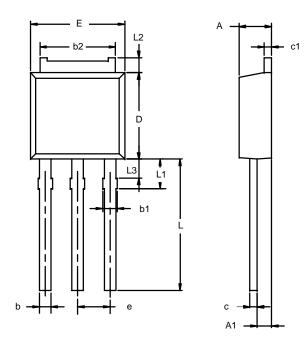
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

| | MILLIN | IETERS | INCHES | | |
|---------------------|-------------------|-------------|-----------|-------|--|
| Dim | Min | Max | Min | Мах | |
| Α | 2.21 | 2.38 | 0.087 | 0.094 | |
| A1 | 0.89 | 1.14 | 0.035 | 0.045 | |
| b | 0.71 | 0.89 | 0.028 | 0.035 | |
| b1 | 0.76 | 1.14 | 0.030 | 0.045 | |
| b2 | 5.23 | 5.43 | 0.206 | 0.214 | |
| С | 0.46 | 0.58 | 0.018 | 0.023 | |
| c1 | 0.46 | 0.58 | 0.018 | 0.023 | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | |
| Е | 6.48 | 6.73 | 0.255 | 0.265 | |
| е | 2.28 BSC | | 0.090 BSC | | |
| L | 8.89 | 9.53 | 0.350 | 0.375 | |
| L1 | 1.91 | 2.28 | 0.075 | 0.090 | |
| L2 | 0.89 | 1.27 | 0.035 | 0.050 | |
| L3 | 1.15 | 1.52 | 0.045 | 0.060 | |
| ECN: S-0 DWG: 53 | 3946—Rev. E 46 | , 09-Jul-01 | • | | |



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